

thereof is requested. A replacement set of formal drawings is being filed herewith, under cover of a Separate Letter to the Official Draughtsperson.

This Preliminary Amendment is accompanied by a Supplemental Information Disclosure Statement. This Supplemental IDS is being filed under 37 CFR 1.97(b) before a first Office Action on the merits and, accordingly it is believed that it qualifies under 37 CFR 1.97.

Restriction

The Examiner required restriction to one of:

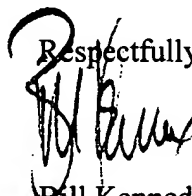
Group I, Claims 1-14, said to be drawn to a "method for connecting a die to a leadframe";

Group II, Claims 15-19, said to be drawn to a "chip-in-leadframe package".

Applicants elect Group I, claims 1-14, for prosecution in this application.

It is believed that no extension of time or fee therefor is required in connection with the filing of this paper. If the Examiner determines that an extension of time is required in connection with the filing of this paper, petition is hereby made therefor, and the Commissioner is authorized to charge the fee to Deposit Account 50-0869 (Order No. CPAC 1001-1).

If the Examiner determines that a conference would facilitate prosecution of this application, the Examiner is invited to telephone Applicants' representative, undersigned, at the telephone number set out below.

Respectfully submitted,  
  
Bill Kennedy  
Reg. No. 33,407

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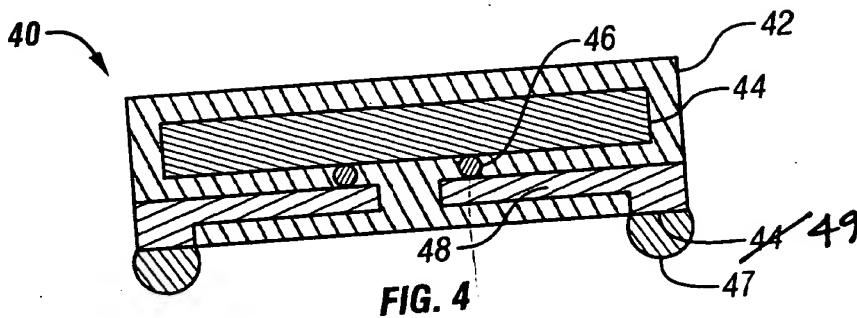
APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

Title: Flip chip-in-leadframe package and process

Inventor: Pendse et al.  
Appln. No. 09/802,443



2/2



CAV. DOWN

